

66. The apparatus of claim 42, wherein said photopolymerized portion has a surface having smooth bumps ranging from about 1 micron to about 20 microns in both height and width.

67. The apparatus of claim 57, wherein said photopolymerized portion has a surface having smooth bumps ranging from about 1 micron to about 20 microns in both height and width.

68. The mold of claim 64, wherein said photopolymerized portion has a surface having smooth bumps ranging from about 1 micron to about 20 microns in both height and width.

Cancel claims 1-21, and 43-56.

REMARKS

The foregoing amendment enhances the protection sought by applicants. The undersigned respectfully requests substantive examination of this application in view of the above.

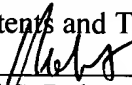
Respectfully submitted,



Richard S. Roberts
Reg. No. 27,941
P.O. Box 484
Princeton, New Jersey 08542
(609) 921-3500
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